

SHRI RAMDEOBABA COLLEGE OF ENGINEERING AND MANAGEMENT, NAGPUR – 440013

An Autonomous College affiliated to Rashtrasant Tukadoji Maharaj Nagpur University, Nagpur, Maharashtra (INDIA)

PROGRAMME SCHEME & SYLLABI 2021 – 2023

M. Tech. (VLSI DESIGN)



Published By

Dr. R. S. Pande

Principal Shri Ramdeobaba College of Engineering & Management Ph. : 0712-2580011 Fax : 0712 - 2583237 ISO 9001 : 2015 CERTIFIED ORGANISATION



About the Department

Department of Electronics Engineering was established in 1986. The Department offers a UG programme in Electronics Engineering and PG programme in M.Tech. (VLSI Design). The National Board of Accreditation; New Delhi has accredited the UG programme four time in succession in the year 2003, 2007, 2013 & 2017 and PG programme in 2016. It is recognized centre for Doctroal programmes of RTM Nagpur University and the department also admits candidates under Visvesvaraya Ph. D scheme. The students undergoes to projects in association with industries. The undergraduate students participate under RGSTC-TIFAC-MSME Internship Program. the department has received a grant of Rs. 10 lakhs from AICTE under its MODROB scheme to carry out projects in CMOS VLSI area. The Department has 16 state of the art labs with investment over Rs. 2 crore. The major sofware include VLSI design, development and verification platforms, such as Mentor Graphics Suite, SDSoC, COMSOL, Xilinx's ISE Development Platform, Tanner tool, ORCAD 15.7. The design Platforms include Virtex 5 Development platform and Embedded System Design environment like NIOS II, Embedded Evaluation CYCLONE III Platform, ARM 7/9/11, Cortex-M0/M4 Development Platforms. Advanced Communication trainers and test equipments include Fiber Optic Trainer, Spectrum Analyzer, Digital Storage Oscilloscope, MIC Trainer, Digital Signal Processors and simulation tools MATLAB 2013 R, Labview 8.0 are also part of the state - of - the art laboratories.

About the Programme

M.Tech (VLSI Design) is a full time two year programme offered by Electronics Engineering Department with an intake of 12 and started in year 2004. Programme is accredited by National Board of Accreditation, New Delhi.

Programme is based on Choice Based Credit System (CBCS) where students can take courses of their choice, learn at their own pace, undergo additional courses, acquire more than the required credits and adopt an interdisciplinary approach to learning. The curriculum is well designed to expose the students to contemporary Digital, Analog, Embedded and RF system design using industry standard EDA tools and development platforms. Dedicated state - of - the - art laboratories include major software and hardware platforms for VLSI Design. Software tools such as Mentor Graphics backend and frontend suit, Tanner Tool, Keil MDK, COMSOL, SDSoC and hardware development platforms such as Xilinx, Altera, Freescale, Cypress, Texas are available.

In order to prepare post graduates to take gainful employment in core, allied sectors of Electronics Engineering, R & D organization and entrepreneurship, the curriculum components include hands-on training, core-elective courses and industry oriented projects.

Students undergo their internship at various R & D organizations, reputed academic institutions and industries such as Indian Nano-electronics Users Program (INUP) at IIT Bombay, IIT Hyderabad, IIT Gandhinagar, ISRO, BARC, Godrej, NEERI, IIIT Jabalpur, VNIT Nagpur, Sankalp Semiconduction, Wizchip Design Technologies, RRCAT Indore etc.



Vision of Department

Electronics Engineering Department endeavors to facilitate state of the art technical education in the field of electronic engineering by infusing scientific temper in students leading towards research and to grow as centre of excellence in the field of microelectronics.

Mission of Department

- To promote quality education through stimulating environment for dissemination of knowledge and technology.
- To impart necessary technical, professional skills with moral and ethical values to enable students for achieving a successful career.
- To develop centre of excellence in the field of microelectronics and its allied areas with continuing education program.
- To foster research and development in collaboration with institutions / industires.

Programme Objectives

- 1. To develop graduates with an ability to design and analyze VLSI Systems.
- 2. To prepare graduates to adapt to the evolving technical challenges by acquiring necessary skills to excel in their career.
- 3. To encourage life-long learning with commitment to ethical practices.

Programme Outcomes

PO1: An ability to apply knowledge of VLSI Design to solve engineering problems.

PO2: An ability to acquire skills to interpret, analyze and evaluate problems of VLSI Systems

PO3 : An ability to independently carry out research / investigation and development of work to solve socio - economic problems.

PO4 : An ability to write and present a substantial technical report /document.





Scheme of Examination of Master of Technology (VLSI Design) Semester Pattern

					S	Maxin	num Marl	(5	Exam Duration (Hrs)	Category
Sr. No.	Code	Course	L	Р	Credit	Internal Assessment	End Semester Exam	Total		
1	ENT571	CMOS Digital Circuit Design	3	0	3	40	60	100	3 Hrs.	PC
2	ENT572	Digital System Design	3	0	3	40	60	100	3 Hrs.	PC
3	ENT573	Semiconductor Devices	3	0	3	40	60	100	3 Hrs.	PC
4	ENT574	Embedded System and RTOS	3	0	3	40	60	100	3 Hrs.	PC
5	ENT575	Programme Elective - I	3	0	3	40	60	100	3 Hrs.	PE
6	ENP571	CMOS Digital Circuit Design Lab	0	2	1	25	25	50		PC
7	ENP572	Digital System Design Lab	0	2	1	25	25	50		PC
8	ENP576	Lab Practice - I	0	2	1	25	25	50		PC
9	ENP574	Embedded System & RTOS Lab	0	2	1	25	25	50		PC
10	ENT577	Audit Course - I	2	0	0				SF/USF	AC
		Total	17	8	19					

I Semester M. Tech. (VLSI Design)

Sr No	Course Code	Programme Elective-1
1	ENT575-1	MEMS Design and Fabrication
2	ENT575-2	Advanced Computer Architecture
3	ENT575-3	Advanced Digital Signal Processing
4	ENT575-4	Hardware Assisted Security
4	ENT575-5	Machine Learning



Scheme of Examination of Master of Technology (VLSI Design) Semester Pattern

II Semester M. Tech. ((VLSI Design)
------------------------	---------------

					ts	Maxin	num Marl	(\$	Exam Duration (Hrs)	Category
Sr. No.	Code	Course	L	Р	Credit	Internal Assessment	End Semester Exam	Total		
1	ENT578	Analog IC Design	3	0	3	40	60	100	3 Hrs.	PC
2	ENT579	System Verilog for Verification	3	0	3	40	60	100	3 Hrs.	PC
3	ENT580	Programme Elective - II	3	0	3	40	60	100	3 Hrs.	PE
4	ENP581	Programme Elective - III	3	0	3	40	60	100	3 Hrs.	PE
5	ENP578	Analog IC Design Lab	0	2	1	25	25	50		PC
6	ENP579	System Verilog for Verification Lab	0	2	1	25	25	50		PC
7	ENP582	Lab Practice - II	0	2	1	25	25	50		PC
8	ENT599	Open Elective-I	3	0	3	40	60	100	3 Hrs.	OE
9	ENP583	Seminar	0	2	1	50		50		PC
10	ENT584	Audit Course - II	2	0	0				SF/USF	AC
		Total	17	8	19					

Course Code	Programme Elective - II / III
ENT580-1/ENT581-1	VLSI Signal Processing
ENT580-2/ENT581-2	RF Circuit Design
ENT580-3/ENT581-3	Memory Technologies
ENT580-4/ENT581-4	Flexible Electronics and Sensors
ENT580-5/ENT581-5	Embedded Machine Learning
ENT580-6/ENT581-6	VLSI Physical Design
ENT580-7/ENT581-7	Industry Elective

Course Code	Open Elective - I
ENT599-2	Digital System Design with FPGA

Course Code	Audit Course - I / II
ENT577-1/ENT584-1	Technical Communication
ENT577-2/ENT584-2	Innovation and Entrepreneurship
ENT577-3/ENT584-3	Personality Development



Scheme of Examination of Master of Technology (VLSI Design) Semester Pattern

III Semester M. Tech. (VLSI Design)

		Code Course L P		ß	Maxin	num Marl	(5	Evam		
Sr. No.	Code		L	Р	Credi	Internal Assessment	End Semester Exam	Total	Duration (Hrs)	Category
1	ENT661	Research Methodology and IPR	2	0	2	40	60	100	3 Hrs.	PC
2	ENT662	Programme Elective - IV	3	0	3	40	60	100	3 Hrs.	PE
3	ENT663	Programme Elective - V	3	0	3	40	60	100	3 Hrs.	PE
4	ENP664	Project Phase - I	0	16	8	50	50	100		PC
		Total	8	16	16					

OR

		s	Maximum Marks			Exam				
Sr. No.	Code	Course	L	Р	Credit	Internal Assessment	End Semester Exam	Total	Duration (Hrs)	Category
1	ENT665	Research Methodology (MOOC /	-	-	2	-	-	100		PC
		Any online platform)								
2	ENP666	Industry Internship / Research Internship	-	-	14	100	100	200		PC
		Total	-	-	16					

Course Code	Programme Elective - IV / V
ENT662-1/ENT663-1	Design for testability
ENT662-2/ENT663-2	SoC Design
ENT662-3/ENT663-3	Nano materials and Nanotechnology
ENT662-4/ENT663-4	Low Power VLSI Design
ENT662-5/ENT663-5	Mixed Signal Processing
ENT662-6/ENT663-6	MOOC - I
ENT662-7/ENT663-7	MOOC - II

05



Scheme of Examination of Master of Technology (VLSI Design) Semester Pattern

IV Semester M. Tech. (VLSI Design)

	Code Course L P	s	Maximum Marks			Fyam				
Sr. No.		Course	L	Р	Credit	Internal Assessment	End Semester Exam	Total	Duration (Hrs)	Category
1	ENP667	Project Phase II	0	28	14	150	150	300		PC
		Total	0	28	14					

		Course L P	s	Maximum Marks			Exam			
Sr. No.	Code		L	Р	Credit	Internal Assessment	End Semester Exam	Total	Duration (Hrs)	Category
1	ENP668	Industry Internship/Reserach Internship	0	0	14	150	150	300		PC
		Total	0	0	14					

OR



Syllabus for Semester I, M.Tech

(VLSI Design)

Course Code : ENT571

L: 3 Hrs., P: 0 Hrs., Per week

Course : CMOS Digital Circuit Design Total Credits : 3

Course Outcomes

Upon completion of this course, students should demonstrate the ability to:

- I. Apply the circuit models to investigate CMOS circuits.
- II. Design moderately sized CMOS circuits/ sub-systems and compute timing, power and parasitic for various CMOS Logic structures.
- III. Evaluate various micron, deep sub-micron and nanometer-scale technologies.

Syllabus

Introduction to MOS Transistors, Switches, CMOS Logic, Scaling and transistors structures for VLSI; Silicon-on-insulator transistors.

Static Load MOS Inverters, CMOS Inverter, the Tri State Inverter.

Circuit Characterization and Performance Estimation : Introduction, Resistance Estimation Capacitance Estimation, Switching Characteristics, Transistor Sizing, Power Dissipation, Sizing Routing Conductors, Charge Sharing.

CMOS Circuit And Logic Design : CMOS Logic Gate Design, CMOS Logic Structures, Clocking Strategies, I/O Structures, Driving Large capacitive loads.

CMOS Sub System Design : Data Path Operations-Addition/Subtraction, Parity Generators, Comparators, Binary Counters, ALUs, Multiplication, Shifters, Memory Elements, Control-FSM, Control Logic Implementation.Memory elements: Read, write memory, RAM, Register files, FIFO, LIFO, SIPO, Serial access Memory, CAM, ROM.

Text Books

- 1. Principles of CMOS VLSI Design: N. Weste and K. Eshranghian, , Addison Wesley, 2 nd Edition
- 2. Digital Integrated Circuits: A Design Perspective: J. Rabaey, PHI, 2 nd Edition
- 3. Basic VLSI Systems and Circuits: Dougles Pucknell and K. Eshraghian PHI, 3rd Edition

- 1. VLSI Analog and Digital Circuit Design Techniques: Randel & Geiger TMH
- 2. Introduction to VLSI System: Carver Mead, Lynn Conway, Addison-Wesley, 1st Edition
- 3. CMOS Digital Integrated Circuits Analysis & Design: S M Kang, Yusuf Lablebici, TMH, 3rd Edition (2003)





Syllabus for Semester I, M.Tech

(VLSI Design)

Course Code : ENP571

L: 0 Hrs., P: 2 Hrs., Per week

Course : CMOS Digital Circuit Design Lab Total Credits : 1

Practicals/ Case Studies/ Mini projects based on syllabus of ENT571



Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT572

L: 3 Hrs., P: 0 Hrs., Per week

Course : Digital System Design Total Credits : 3

Course Outcome

Upon the completion of this course, students will demonstrate the ability to:

- I. Model and test the digital designs
- II. Describe the digital system design flow
- III. Write a optimize and synthesizable HDL code
- IV. Analyze the timing issues and implement the digital logic on various programmable devices

Syllabus

Hardware Description Languages

Introduction to HDL : Basic Language Elements, Syntax and Semantics HDL, Modeling Styles for building blocks, use of Procedures –functions / Task –function in designs, Attributes, Writing Test Benches, Handling Text files, Combinational & Sequential Design examples :Adders, Multipliers, ALU, Memories, FSM, FIFO

System Design Flow : Top-Down and Bottom-Up methodology, Word Length Determination, Data Path Control Path, Implementation of DSP algorithm

Synthesis- Analysis and Introduction to Optimization Techniques: Methodology, Logic Synthesis of HDL, Critical Path analysis, Speed, Area and Power optimizations at Architectural level,

Timing and Signal Integrity : Timing Basics and Signal integrity, Dealing with Clock Skew and Jitter, Synchronizers

Programmable ASICs: Technology Overview, CLBs, Architecture, Realization of functions in FPGA

Text Books

- 1. A VHDL Primer, Third Edition: J. Bhasker, Prentice Hall, (1999).
- 2. Verilog HDL: A guide to Digital Design and Synthesis: Samir Palnitkar, Prentice Hall(1996)
- 3. Advanced Digital Design with the Verilog HDL: M.D. Ciletti, Prentice Hall, (2003).
- 4. Synthesis and Optimization of Digital Circuits, G. De Micheli, McGraw-Hill, (1994).



- 1. The Verilog Hardware Description Language, Fifth Edition: Donald E. Thomas, Philip R. Moorby, Kluwer Academy Publisher. (2002).
- 2. Digital Systems Design Using VHDL, Second Edition: Charles H. Roth. Jr., L Kurian John, Cengage Learning, (2008).
- 3. Logic Synthesis using Synopsys, Second edition, P. Kurup and T. Abbasi, Kluwer, (1996)
- 4. Logic synthesis and verification algorithms: Gray D. Hachtel, Fabio Somenzi, Springer (1996)
- 5. An Engineering Approach to Digital Design: W. Fletcher. Prentice Hall



Received and and a second and a

Shri Ramdeobaba College Of Engineering and Management, Nagpur

Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENP572

Course : Digital System Design Lab

L: 0 Hrs., P: 2 Hrs., Per week

Total Credits : 1

Practical / Case Studies/ Mini projects based on syllabus of ENT572





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT573

Course : Semiconductor Devises Total Credits : 3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon completion of this course, students should demonstrate the ability to

- I. Utilize semiconductor models to analyze carrier densities and carrier transport.
- II. Understand and utilize the basic governing equations to analyze semiconductor devices.
- III. Understand and analyze the working of semiconductor p-n diodes, Schottky barrier diodes and advanced MOSFET technology.

Syllabus

Basic Semiconductor Physics

Crystal lattice, energy band model, density of states, distribution statics – Maxwell-Boltzmann and Fermi-Dirac, doping, carrier transport mechanisms, drift, diffusion, thermionic emission, and tunneling; excess carriers, carrier lifetime, recombination mechanisms – SHR, Auger.

p-n junction and metal-semiconductor junction

p-n junctions- fabrication, basic operation – forward and reverse bias, DC model, charge control model, I-V characteristics, steady-state and transient conditions, capacitance model, reverse-bias breakdown, SPICE model; metal-semiconductor junctions –fabrication, Schottky barriers, rectifying ad ohmic contacts, I-V characteristics.

MOS Capacitors and MOSFETs

The MOS capacitor – fabrication, surface charge – accumulation, depletion, inversion, threshold voltage, C-V characteristics – low and high frequency; the MOSFET – fabrication, operation, gradual channel approximation, simple charge control model (SCCM), Pao-Sah and Schichman – Hodges models, I-V characteristics, second-order effects – Velocity saturation, short-channel effects, charge sharing model, hot-carrier effects, gate tunneling; subthreshold operation – drain induced barrier lowering (DIBL) effect, unified charge control model(UCCM), SPICE level 1, 2, and 3, and Berkeley short-channel IGFT model (BSIM).

Advanced MOSFET technology: SOI MOSFET, high-k MOS devices, FinFETs and Multi gate MOSFETs



Text Books

- 1. Physics of Semiconductor Devices: S. M. Sze, Wiley Eastern, (1981).
- 2. Semiconductor physics and Devices, Donald Neamen, McGraw-Hill, 3rd edition
- 3. Solid State Electronic Devices , B.G. Streetman and S.Banerjee , Prentice Hall India

Reference Books

1. CMOS Circuit Design, Layout and simulation: J. Baker, D.E. Boyce., IEEE press.





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT574

Course : Embedded System and RTOS L: 3 Hrs., P: 0 Hrs., Per week **Total Credits : 3**

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- Apply the knowledge of ARM architecture and organization for modern ARM Cortex-M devices. Ι.
- Utilize knowledge, techniques and skill to integrate hardware and software component using П. Cortex-M.
- III. Apply the concepts of Embedded OS.
- IV. Design an embedded system for given constraint

Syllabus

Introduction to Embedded Systems, Concepts, Embedded System Design Issues. RISC Principles.

The Cortex - M processor : Applications, Simplified view – block diagram, programming model – Registers, Operation modes, Exceptions and Interrupts, Reset Sequence, Instruction Set, Unified Assembler Language, Pipeline, Bus, Priority, Vector Tables, Interrupt Inputs and Pending behavior, Fault Exceptions, Supervisor and Pendable Service Call, Nested Vectored Interrupt Controller, SYSTICK Timer, Interrupt Sequences, Introduction to the Cortex microcontroller software interface standard (CMSIS), Interfacing of GPIOs, Timers, ADC, UART and other serial interfaces, PWM.

Concept and Fundamentals of RTOS: RTOS examples, Interrupts, Handling an Interrupt, Interrupt Service Routines, Context Switching, Process States, Communication Mechanism, SchedulingAlgorithm, Priority Inversion, Priority Inheritance. Inter-task Communication: Shared Variables, Monitors, Messages, Events, Semaphores, Priority inversion problem, Deadlocks, Starvation.

Concepts, Structure of µCOS - II : - Kernel Structure: Tasks, Task States, TCB, Ready List, Task Scheduling, Interrupts, Clock Tick, Initialization, Starting the OS, Task Management, Time Management, Event Control Blocks, Synchronization in µCOS - II: - Semaphore Management, Mutual Exclusion Semaphores, Event Flag Management, Communication in µCOS - II: - Message Mailbox Management, Message Queue Management, Memory management, Porting of µCOS – II

Linux as an embedded OS, Tools and development, Applications and products, Building Linux Kernel



Text Books

- 1. The Definitive Guide to the ARM Cortex-M0 : Joseph Yiu, Elsevier ,(1/E)2011
- 2. An Embedded software primer: David E Simon, Pearson education Asia, 2001
- 3. Micro C/OS II The Real Time Kernel: Jean J. Labrosse, CMPBooks, (2/E) 2002
- 4. Embedded Linux Primer: christopher Hallinan, Pearson (1/E) 2007

- 1. ARM System Developer's Guide Designing and Optimizing System Software: Andrew N. Sloss, Dominic Symes, Chris Wright, Morgan Kaufmann publications, (1/E) 2004.
- 2. ARM system on chip Architecture: Steve Furber, Person Education Addison Wesley, (2/E) 2000





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENP574

Course : Embedded System and RTOS Lab

_ .

L:0 Hrs., P:2 Hrs., Per week

Total Credits : 1

Practicals/ Case Studies/ Mini projects based on syllabus of ENT574





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENP576

Course : Lab Practice - I Total Credits : 1

L: 0 Hrs., P: 2 Hrs., Per week

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- I. Apply fundamental principles to solve problems
- II. Design and execute an experimental procedure, work independently, interpret experimental results
- III. Draw a reasonable, accurate conclusion using suitable tools and technique

Practical / Case Studies / Mini projects





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT575-1

L: 3 Hrs., P: 0 Hrs., Per week

Course : MEMS Design and Fabrication Total Credits : 3

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to

- I. Apply the principles behind the operation of MEMS devices
- II. Choose a micromachining technique for a specific MEMS fabrication process
- III. Design and fabricate MEMS devices or a microsystem
- IV. Understand recent advancements in the field of MEMS and devices.

Syllabus

Micro-fabrication and Micromachining : Integrated Circuit Processes, Bulk Micromachining: Isotropic Etching and Anisotropic Etching, Wafer Bonding, High Aspect-Ratio Processes (LIGA)

Physical Micro-sensors : Classification of physical sensors, Integrated, Intelligent, or Smart sensors, Sensor Principles and Examples : Thermal sensors, Electrical Sensors, Mechanical Sensors, Chemical and Biosensors

Micro-actuators : Electromagnetic and Thermal micro-actuation, Mechanical design of microactuators, Micro-actuator examples, micro-valves, micro-pumps, micro-motors-Micro-actuator systems : Success Stories, Ink-Jet printer heads, Micro-mirror TV Projector

Surface Micromachining : One or two sacrificial layer processes, Surface micromachining requirements, Polysilicon surface micromachining, Other compatible materials, Silicon Dioxide, Silicon Nitride, Piezoelectric materials, Surface Micromachined Systems: Success Stories, Micromotors, Gear trains, Mechanisms

Application Areas : All-mechanical miniature devices, 3-D electromagnetic actuators and sensors, RF/Electronics devices, Optical/Photonic devices, Medical devices e.g. DNA-chip, micro-arrays.

MEMS for RF Applications : Need for RF MEMS components in communications, space and defense applications.

Text Books

- 1. Micro and Smart Systems, Ananthasuresh, G. K., Vinoy, K. J. Gopala Krishnan, S., Bhat, K. N., Aatre, V. K., Wiley-India, New Delhi, 2010. 1st Edition
- 2. RF MEMS and Their Applications: Vijay. Varadan, K. J. Vinoy, K. A. Jose, Wiley, 2002, 1 st Edition.





- 1. Microsensors, MEMS and Smart Devices, Julian W. Gardner, Vinay K. Varadan, Osama O. Awadelkarim, Wiley, 2001, 1st Edition
- 2. VLSI Technology, Sze S. M., Mc Graw Hill, 2nd Edition





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT575-2

Course : Advanced Computer Architecture Total Credits : 3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to

- I. Define the principles of computer design and its performance enhancement measures.
- II. Describe the operations of performance such as pipelines, dynamic scheduling branch predictions, caches.
- III. Describe the modern architecture such as RISC, Scalar, VLIW, Multi core and multi CPU systems.
- IV. Compare the performance of different computer architectures.
- V. Develop the applications for high performance computing systems.
- VI. Appraise memory organizations and modern computer architectures.

Syllabus:

- Classes of computers, Trends in technology, power and costs, dependability, quantitative principles of computer design, Models of parallel computer, multiprocessors and multi-computers, multi-vector and SIMP computers, PRAM and VLSI model, conditions of parallelism, data and resource dependencies, grain size and latency, grain packing and scheduling, program flow mechanisms, system interconnect architectures.
- Principles of scalable performance, performance metrics and measures, speedup performance laws, advanced processor technology, superscalar and vector processors, cache memory organizations, shared memory organizations.
- Pipeline and superscalar techniques, linear pipeline processors, reservation and latency analysis, collision free scheduling, pipeline schedule optimization, instruction pipeline design, arithmetic pipeline design, superscalar and super-pipeline design.
- Multiprocessors and multi computers, multiprocessor system interconnects, cache coherence and synchronization mechanisms, message passing schemes.
- Multi-vector and SIMD computers vector processing principles, compound vector processing, SIMD computer organizations scalable multithreaded and dataflow architectures.
- Elementary theory about dependence analysis, techniques for extraction of parallelism.



Text Books

- 1. Advanced Computer Architecture: Kai Hwang; McGraw Hill.
- 2. Computer Architecture: A Quantitative Approach: J. Hennessy and D. Patterson, Morgan Kaufmann, 3rd edition, 2003.
- 3. Advanced Computer Architecture and Computing: S.S. Jadhav, Technical Publication, Pune

- 1. Advanced Computer Architectures: A Design Space Approach: Dezso Sima, Terence Fountain, Peter Karsuk, Pearson Education, 1st edition, 1997.
- 2. Advanced Computer Architecture: Richard Y. Kausi; Prentice Hall of India





Syllabus for Semester I, M.Tech

(VLSI Design)

Course Code : ENT575-3

Course : Advanced Digital Signal Processing Total Credits : 3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- I. Analyze the multirate digital signal processing architectures
- II. Describe the architecture of programmable DSP processor
- III. Reduce the computational complexity of the signal processing algorithms
- IV. Illustrate the applications of DSP

Syllabus

Basics of Signal Processing and Multirate Signal Processing

Basics of signal Processing, Multirate Signal Processing: analysis of multirate structures, multistage design of decimator and interpolator, computationally efficient interpolator and decimator structures, Design of linear phase/poly-phase FIR filters.

Programmable DSP (P-DSP) Processor

Evolution of (P-DSP) processors and features, multiport memory, Architectural structural of (P-DSP) :MAC units, Barrel Shifters, Introduction to DSP processor family for multimedia signal processing ,SIMD, MIMD, VLIW architecture,

Algorithmic strength Reduction in Filters

Parallel FIR filters: formulation using polyphase decomposition, Fast FIR algorithms Algorithm - Architecture Transformation: DCT-IDCT

Parallel Architecture for Rank order filters

Applications of DSP

Dual Tone Multifrequency Signal Detection, Spectral Analysis of Sinusoidal signal and non stationary signals Sound Processing : echo filtering, reverberator architecture, flanging, chorus generator.

Oversampling A/D and D/A convertor



Text Books

- 1. Digital Signal Processing : Principles, Algorithms and Applications PHI publications 4th Edition, John G. Proakis, Dimitris G. Manolakis
- 2. VLSI Digital Signal Processing Systems: Design and Implementation Wiley India Edition, By K.K. Parhi
- 3. Digital Signal Processing : A computer Based Approach , Mcgraw Hill 3rd Edition , By Sanjit K Mitra

Reference Books

1. Discrete Time Signal Processing, Pearson Prentice Hall India , 2nd edition, A.V. Oppenheim, R.W. Schaefer





Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT575-4

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

After completion of the course student will be able to:

- I. Understand main security primitives typically used to develop defense mechanisms.
- II. Examine different performance parameters of hardware security primitives.
- III. Analyze attacks on security primitives & possible countermeasures.
- IV. Evaluate different security applications.

Syllabus

Primer on Cryptographic Primitives & Security Attacks: known security attacks on electronics systems, main cryptographic primitives typically used to develop defense mechanisms, motivation behind the development of hardware-based security solutions, physically unclonable functions(PUF).

PUFs Design Principles & Evaluation Metrics: the concept of physical disorder, PUF device using integrated circuit design techniques, the important metrics employed to assess the quality and usability of PUF circuit architectures.

Reliability Challenges of Silicon-based PUFs: The physical mechanisms of CMOS aging, typical temporal failure mechanisms, including radiation hits, electromagnetic interference, thermal noise, case study, Reliability Enhancement Techniques for PUFs.

Security Attacks on PUFs & possible Countermeasures: The design qualities one should consider when evaluating the security of a PUF design, adversary classification, principles of machine learning algorithms and how these can be employed to realize mathematical cloning attacks, side channel attacks.

Hardware-based Security Applications: Key generation, Authentication, Anti-counterfeiting Techniques.

Reference Books

- 1. Christof Paar, Jan Pelzl, "Understanding Cryptography", 2nd edition Springer, 2010.
- 2. Jonathan Katz and Yehuda Lindell, "Introduction to Modern Cryptography", 3rd Edition, CRC Press, 2021.
- 3. Ahmad-Reza Sadeghi, David Naccache, Pim Tuyls, "Towards Hardware-Intrinsic Security: Foundations and Practice" Springer, 2014
- 4. Roel Maes, "Physically Unclonable Functions Constructions, Properties and Applications", Springer, 2014.
- 5. IEEE Transactions on Information Forensics and Security.



Course : Hardware Assisted Security Total Credits : 3

Syllabus for Semester I, M.Tech (VLSI Design)

Course Code : ENT575-5

Course : Machine Learning Total Credits : 3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon successful completion of the course, students will be able to:

- I. Understand the fundamental concepts of machine learning, and get an insight of when to apply a particular machine learning approach.
- II. Comprehend the underlying mathematical relationship within/across Machine Learning algorithms.
- III. Apply machine-learning algorithms to complex engineering problems, optimize the models learned and report on the expected accuracy that can be achieved by applying the models.
- IV. Design and implement deep neural networks for solving real-world problems in various domains and test them with benchmark data sets.

Syllabus

Foundations and paradigms of Machine Learning

Supervised learning : K-Nearest Neighbors, Decision trees, Linear and Logistic Regression – Bias/Variance Trade-off, Overfitting, Regularization, Variants of Gradient Descent, Support Vector Machines, boosting and bagging, Ensemble methods such as Random Forest and Ada Boost.

Artificial Neural Networks

Perceptron, Multilayer networks, Backpropagation algorithm, Optimization algorithms, Introduction to Deep Neural networks, Convolutional Neural Networks (CNNs) and Recurrent Neural Networks (RNNs), Brief introduction to ML applications in computer vision, and natural language processing using Tensorflow/Pytorch.

Probabilistic Machine Learning

Bayesian learning and Bayesian networks, Naive Bayes classifier; Bayes optimal classifiers, Maximum Likelihood Estimation, MAP; Gaussian Discriminant Analysis.

Unsupervised learning

Clustering, Expectation Maximization, and Gaussian Mixture Models. Dimensionality Reduction-PCA, LDA, and Feature Selection, PAC Learnability.

Text Book

- 1. Understanding Machine Learning: From Theory to Algorithms, by Shai Shalev-Shwartz, Shai Ben-David, Third edition, Cambridge University Press, 2015.
- 2. Pattern Recognition and Machine Learning by Christopher M. Bishop, First edition, Springer, 2006.
- 3. The Elements of Statistical Learning Data Mining, Inference, and Prediction by Trevor Hastie, Robert Tibshirani, Jerome Friedman, Second Edition, Springer, 2009.

- 1. Machine learning, by Mitchell Tom, First edition, McGraw Hill, 1997.
- 2. Deep Learning by Ian Goodfellow, Yoshua Bengio, Aaron Courville and Francis Bach, MIT Press, 2017.
- 3. Machine Learning: An Algorithmic Perspective by Stephen Marsland, Second Edition, Chapman and Hall/CRC, 2014.
- 4. Richard O. Duda, Peter E. Hart, David G. Stork. Pattern classification, Wiley, New York, 2001.
- 5. Machine Learning: A Probabilistic Perspective by Kevin P. Murphy, Francis Bach; MIT Press, 2012.
- 6. Recent Research Papers from Reputed Journals and Conferences such as ICLR, NIPS, ICML, CVPR, PAMI etc.



Syllabus for Semester II, M.Tech (VLSI Design)

Course Code : ENT578

Course : Analog IC Design Total Credits : 3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- I. Understand basics of data converters
- II. Apply mathematical models of MOS transistors to evaluate their behavior in analog circuits.
- III. Analyze MOS based analog building blocks
- IV. Evaluate various analog IC performance parameters.
- V. Design CMOS analog circuits by taking suitable design approaches for given specifications

Syllabus

Introduction to Analog VLSI and Analog design issues in CMOS technologies

Basic analog building blocks : Switches, Active resistors, current, voltage sources and sinks, current mirrors, current and voltage reference, Bandgap references.

Amplifiers, Common Source, Source follower, Common Gate and Cascode amplifiers, Frequency Response.

Frequency Response of Amplifiers : Miller Effect, Association of Poles with nodes, Frequency Response of all single stage amplifiers

Differential Amplifier : Basic differential Pair, common mode response, CMRR, Differential Pair with MOS load, Gilbert Cell.OPAMP Design: Single stage and two Stage OP-Amps, Frequency compensation.

Switch Capacitor circuits : General considerations, sampling switches, Switched capacitor integrator.

Data Converter Fundamentals : DAC/ADC Specifications, Data Converter Architectures: DAC architectures, Resistor String, Charge-Scaling DACs, Cyclic DAC, Pipeline DAC.ADC Architectures-Flash, The Two-Step Flash ADC, The Pipeline ADC, Integrating ADCs, The Successive Approximation ADC.



Text Books

- 1. Design of Analog CMOS IC: B Razavi, Tata Mcgrw Hill (2002)
- 2. CMOS Circuit Design, Layout and simulation: J. Baker, D.E. Boyce., IEEE press (2010).
- 3. VLSI Design techniques for Analog and digital Circuits: R.L. Geiger, P.E. Allen, D. R. Holberg, OUP, (2/E) McGraw Hill (2002)

- 1. VLSI Design techniques for Analog and digital Circuits: Randel Geiger, P Allen, N Strader, Tata Mcgraw, Hill, (2/E) (2010)
- 2. Analysis And Design Of Analog ICs : Paul R. Gray, Paul J. Hurst Stephen H. Lewis, Robert G. Meyer, J, Willy and Sons, (4/E) (2001)





Syllabus for Semester II, M.Tech (VLSI Design)

Course Code : ENP578

Course : Analog IC Design Lab

L: 0 Hrs., P: 2 Hrs., Per week

Total Credits : 1

Practicals/ Case Studies/ Mini projects based on syllabus of ENT578





Syllabus for Semester II, M.Tech (VLSI Design)

Course : System Verilog for Verification

Total Credits : 3

Course Code : ENT579

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

Upon completion of this course, students should demonstrate the ability to

- I. Describe the advantages and enhancements to System Verilog to support verification
- II. Describe object-oriented programming and create a class-based verification environment
- III. Utilize assertions to quickly identify correct behavior in simulation
- IV. Create and utilize random data generation and functional coverage features of system verilog for simulation verification

Syllabus

Verification Guidelines : Introduction, Verification Process, Verification Plan, Verification Methodology Manual, Basic Testbench Functionality, Directed Testing, Methodology Basics, Constrained-Random Stimulus, Functional Coverage, Testbench Components, Layered Testbench,

Data Types : Built-in Data Types, Fixed-Size Arrays, Dynamic Arrays, Queues, Creating New Types with typedef, Creating User-Defined Structures, Enumerated Types, Constants, Strings

Procedural Statements and Routines: Procedural Statements, Tasks, Functions, and Void Functions.

Basic Oop: Where to Define a Class, OOP Terminology, Understanding Dynamic Objects.

SystemVerilog Assertions: Types of Assertions and examples.

Threads and Inter-process Communication: Working with Threads, Inter-process Communication, Events, Semaphores, Mailboxes, Building a Testbench with Threads and IPC

Functional Coverage : Coverage Types, Functional Coverage Strategies, Simple Functional Coverage Example, Coverage Options, Parameterized Cover Groups, Analyzing Coverage Data, Measuring Coverage Statistics during Simulation

Introduction to Perl – Learning perl, how can it be used for automation

Text Books

- 1. System Verilog for Verification: A Guide to Learning the Test bench Language Features, Chris Spear, Springer 2006
- 2. Writing Test benches Using System Verilog, Janick Bergeron, Springer, 2006
- 3. System Verilog for Design: A Guide to Using System Verilog for Hardware Design and Modeling, 2nd Edition, Stuart Sutherland, Simon Davidman and Peter Flake, Springer



- 1. Writing Test benches: Functional Verification of HDL Models, Second edition, Janick Bergeron, Kluwer Academic Publishers, 2003.
- 2. Open Verification Methodology Cookbook, Mark Glasser, Springer, 2009
- 3. Principles of Functional Verification, Andreas S. Meyer, Elsevier Science, 2004
- 4. Assertion-Based Design, 2nd Edition, Harry D. Foster, Adam C. Krolnik, David J. Lacey, Kluwer Academic Publishers, 2004.





Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENP579

Course : System Verilog for Verification Lab

L: 0 Hrs., P: 2 Hrs., Per week

Total Credits : 1

Practical / Case Studies/ Mini projects based on syllabus of ENT579



Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-1/ENT581-1Course : VLSI Signal ProcessingL : 3 Hrs., P : 0 Hrs., Per weekTotal Credits : 3

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- 1. Apply the concepts of pipelining, parallel processing, retiming, folding and unfolding to optimize digital signal processing architectures.
- II. Analyze data flow in systolic architectures.
- III. Minimize the computational complexity using fast convolution algorithms.

Syllabus

Introduction to Digital Signal Processing Systems

Introduction, Typical DSP Algorithms, Representations of DSP Algorithms.

Iteration Bound

Introduction, Data Flow Graph Representations, Loop Bound and Iteration Bound, Algorithms for Computing Iteration Bound, Iteration Bound of Multirate Data Flow Graphs.

Pipelining and Parallel Processing

Introduction, Pipelining of FIR Digital filters, Parallel Processing. Pipelining and Parallel Processing for Low Power.

Retiming: Introduction, Definitions and Properties, Solving System of Inequalities, Retiming Techniques. Unfolding: Introduction, An algorithm for Unfolding, Properties of Unfolding, Critical Path, Unfolding and Retiming, Applications of Unfolding.

Folding

Introduction, Folding Transformation, Register Minimization Techniques, Register Minimization in Folded Architectures, Folding of Multirate Systems.Systolic Architecture Design: Introduction, Systolic Array Design Methodology, FIR systolic Arrays, Selection of scheduling vector, Matrix-Matrix Multiplication and 2D Systolic Array Design, Systolic Design for Space Representations containing Delays.

Fast Convolution

Introduction, Cook-Toom Algorithm, Winogard Algorithm, Iterated Convolution, Cyclic Convolution, Design of Fast Convolution Algorithm by Inspection.



Text Books

- 1. VLSI Digital Signal Processing Systems: Keshab K. Parhi. Wiley-Inter Sciences. (1999).
- 2. Analog VLSI signal and information processing: Mohammed Ismail, Terri, Fiez, McGraw Hill. (1994).
- 3. VLSI Digital signal processing system Design and implementation: Keshab. Parthi, Wiley-Inter science, (1999).

- 1. VLSI and Modern signal processing: kung. S. Y., H. J. While house T. Kailath, prentice hall, (1985).
- 2. Design of Analog Digital VLSI circuits for telecommunications and signal processing: Jose E. France, Yannis Tsividls, prentice Hall, (1994).



Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-2/ENT581-2

L: 3 Hrs., P: 0 Hrs., Per week

Course : RF Circuit Design Total Credits : 3

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- I. Understand the architectures, operation and performance specifications/ tradeoff of a RF receiver and its building blocks.
- II. Design and analyze impedance transformation networks using passive elements with smith charts and hand calculation.
- III. Understand and evaluate various performance specifications for individual blocks of receiver like filters, LNA, Mixer, Power Amplifiers by hand calculations.
- IV. Understand the sources of nonlinearity, noise, process technology and its impact on the performance parameters of individual blocks of receiver and on receiver performance.
- V. Demonstrate the tools and techniques to evaluate the performance specifications of RF building blocks.

Syllabus

Characteristics of passive components for RF circuits. Passive RLC networks. Transmission lines. Twoport network modeling. S-parameter model. The Smith Chart and its applications.

Active devices for RF circuits

SiGe MOSFET, GaAs pHEMT, HBT and MESFET. PIN diode. Device parameters and their impact on circuit performance.

Review of analog filter design

Low-pass, high-pass, band-pass and band-reject filters. RF Amplifier design, single and multi-stage amplifiers.

Low Noise Amplifier design

Noise types and their characterization, LNA topologies, power match vs noise match. Linearity and large-signal performance.

RF Power amplifiers

General properties. Class A, B, AB, C, D, E and F amplifiers. Modulation of power amplifiers.

Analog communication circuits

Mixers, phase-locked loops, oscillators, Transreceiver Architecture and performance specification.

35



Text Books

1. The Design of CMOS Radio Frequency Integrated Circuits: Thomas H. Lee- Cambridge University Press.

- 1. RF Microelectronics: Behzad Razavi-McGraw Hill.
- 2. Design of Analog CMOS integrated circuits: Behzad Razavi-McGraw Hill.
- 3. RF Circuit Design: Theory & Applications: Reinhold Ludwig, Gene Bogdanov



Syllabus for Semester II, M.Tech

(VLSI Design)

Course : Memory Technologies

Total Credits : 3

Course Code : ENT580-3/ENT581-3

L: 3 Hrs., P: 0 Hrs., Per week

Course Outcomes

At the end of the course, students will be able to:

- I. Select architecture and design semiconductor memory circuits and subsystems.
- II. Identify various fault models, modes and mechanisms in semiconductor memories and their testing procedures.
- III. Knowhow of the state-of-the-art memory chip design

Syllabus

Random Access Memory Technologies : Static Random Access Memories (SRAMs), SRAM Cell Structures, MOS SRAM Architecture, MOS SRAM Cell and Peripheral Circuit, Bipolar SRAM, Advanced SRAM Architectures, Application Specific SRAMs.

DRAMs, MOS DRAM Cell, BiCMOS DRAM, Error Failures in DRAM, Advanced DRAM Design and Architecture, Application Specific DRAMs, SRAM and DRAM Memory controllers.

Non-Volatile Memories : Masked ROMs, PROMs, Bipolar & CMOS PROM, EEPROMs, Floating Gate EPROM Cell, OTP EPROM, EEPROMs, Non-volatile SRAM, Flash Memories.

Semiconductor Memory Reliability and Radiation Effects : General Reliability Issues, RAM Failure Modes and Mechanism, Nonvolatile Memory, Radiation Effects, SEP, Radiation Hardening Techniques. Process and Design Issues, Radiation Hardened Memory Characteristics, Radiation Hardness Assurance and Testing.

Advanced Memory Technologies and High-density Memory Packing Technologies : Ferroelectric Random Access Memories (FRAMs), Gallium Arsenide (GaAs) FRAMs, Analog Memories, Magneto Resistive Random Access Memories (MRAMs), Experimental Memory Devices.

Memory Hybrids (2D & 3D), Memory Stacks, Memory Testing and Reliability Issues, Memory Cards, High Density Memory Packaging

Text Book

- 1. Ashok K Sharma," Semiconductor Memories: Technology, Testing and Reliability, PHI 1997
- 2. Kiyoo Itoh, "VLSI memory chip design", Springer International Edition

Reference Book

- 1. Luecke Mize Care, "Semiconductor Memory design & application", Mc-Graw Hill. 2.Belty Prince, "Semiconductor Memory Design Handbook".
- 2. Ashok K Sharma, "Advanced Semiconductor Memories: Architectures, Designs and Applications", Wiley Interscience

37



Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-4/ENT581-4Course : Flexible Electronics and SensorsL : 3 Hrs., P : 0 Hrs., Per weekTotal Credits : 3

Course Outcome

The course will provide an insight of the technology and applications for printed and flexible electronics.

- 1. Acquire and develop basic concepts and understanding of thin-film electronic materials and device processing.
- II. Develop an understanding of emerging materials, processes, device performance, and target applications for electronics, tools for flexible electronic systems
- III. Understand the basic concepts for integration of thin-film devices on flexible platforms

Syllabus

Module - I

Introduction to Flexible Electronics : Background and history, trends, emerging technologies, general applications, Introduction to Semiconductors & Circuit Elements: doping, band structure, thin-film electronic devices

Module - II

Materials for Flexible Electronics : Nanowire and nanoparticle synthesis, metal oxides, amorphous thin films, polymeric semiconductors, structure and property relationships, paper-based electronics, textile substrates, barrier materials,

Module - III

Thin-film Deposition : Processing Methods for Flexible Devices, CVD, PECVD, PVD, etching, photolithography, low-temperature process integration

Module - IV

Solution-based Processes : Ink-jet printing, imprint lithography, spray pyrolysis, gravure, screen printing, multilayer patterning, and film characterization techniques, design rule considerations

Module - V

Contacts and Interfaces: Schottky contacts, Ohmic contact, relevant defects, carrier recombination, conducting polymers, Carbon-based electronics, effect of applied mechanical strain



Module - VI

Applications of Flexible devices and sensors: Thin Film Transistors: device structure and performance, electrical characterization methods for rigid and flexible devices, Displays, Organic sensors and arrays, memory devices, MEMS devices, lab-on-a-chip devices, photovoltaic, wearable sensors, Body/textile antennas, Energy Harvesting devices

Text Books

- 1. William S. Wong, Alberto Salleo, Flexible Electronics: Materials and Applications, 2011, 1st Edition, Springer, New York.
- 2. Subhas Mukhopadhyay, Anindya Nag, Printed and Flexible Sensor Technology: Fabrication and applications, 2021 edition, IOP Series in Sensors and Sensor Systems

Reference Books

- 1. Edward Sazonov, Michael R. Newman, "Wearable Sensors: Fundamentals, Implementation and Applications", 2014, 1st Edition, Academic Press, Cambridge.
- 2. Kate Hartman, "Make: Wearable Electronics: Design, prototype, and wear your own interactive garments", 2014, 1st Edition, Marker Media, Netherlands.

Web Sources

- 1. https://www.standardsuniversity.org/e-magazine/june-2017/fabrication-and-implementationof-wearable-flexi ble-sensors/
- 2. https://www.nature.com/articles/micronano201643





Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-5/ENT581-5

L: 3 Hrs., P: 0 Hrs., Per week

Course : Embedded Machine Learning Total Credits : 3

Course Outcomes

Upon successful completion of the course, students will be able to:

- I. Understand the key design considerations for embedded Machine Learning
- II. Understand tradeoffs between various hardware architectures and platforms
- III. Apply the techniques for designing of efficient hardware for machine learning algorithms
- IV. Develop the DNN using hardware/software framework
- V. Analyze the architecture of DNN accelerators with given target area-power-performance metrics
- VI. Summarise the principles of Problem solving, quantitative and/or qualitative decision making in complex situations

Syllabus

Introduction to Machine Learning, Background and overview on Deep Neural Networks, Training versus Inference ,Applications of DNNs, Embedded versus Cloud, Key Metrics: Accuracy, Throughput and Latency, Energy Efficiency and Power Consumption, Hardware Cost, Flexibility, Scalability, Interplay Between Different Metrics.

Kernel Computation, DNN Accelerators, Operation mapping on specialized hardware

Co-Design of DNN Hardware and Algorithms: Precision reduction, Quantization , Sparsity, Activation and Weight, Compression and sparse dataflow

Computing platform: Processors- GPU, CPU, NPU

Embedded AI devices : PYNQ-Z2, Arduino UNO R3, Intel Movidius NCS2, Raspberry Pi 4, Google Coral USB Accelerator, NVIDIA Jetson Nano

Software Framework : Pytorch, TinyML, Keras, TensorflowAccelerator: Approximate Computing, FPGA-based Accelerators, Sparsity, Reduction precision, Systolic Arrays, HW-SW Co-Design

Case Study: Real world machine learning application and implementation.

Designing of efficient DNN models for Resource constraint applications



Text Book

- 1. Efficient Processing of Deep Neural Networks, Vivienne Sze, Yu-Hsin Chen, Tien-Ju Yang, and Joel S. Emer, Morgan & CLaypool publishers (2020)
- 2. Practical Deep Learning for Cloud, Mobile and Edge: Real-World AI & Computer-Vision Projects Using Python, Keras & Tensorflow by Anirudh Koul, Siddha Ganju, Mehere Kasam, O Reilly; Illustrated edition (2019)

- 1. IoT and Edge Computing for Architects: Implementing edge and IoT systems from sensors to clouds with communication systems, analytics, and security, 2nd Edition, by Perry Lea, Packt Publishing Limited; 2nd Revised edition
- 2. Hardware Architectures for Deep Learning, by Masoud Daneshtalab , Mehdi Modarressi, Institution of Engineering and Technology
- 3. Recent Research Papers from Reputed Journals and Conferences such as CVPR, ICLR, NIPS, ICML, PAMI etc.





Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-6/ENT581-6	Course : VLSI Physical Design
L:3 Hrs., P:0 Hrs., Per week	Total Credits : 3

Course Outcome

Upon successful completion of the course, students will be able to:

- I. Describe the VLSI design flow and various VLSI design styles in detail
- II. Use algorithmic graph theory and combinatorial optimization techniques, as per requirement, to correctly ormulate and solve VLSI design problems
- III. Explain the algorithms for partitioning, floor planning, placement and routing of VLSI circuits and use them to solve simple VLSI design problems.
- IV. Describe the process of Static Timing Analysis of VLSI circuits.

Syllabus

Introduction to VLSI CAD : VLSI design methodologies, use of VLSI CAD tools, Algorithmic Graph Theory and computational Complexity.

High-level Synthesis : Hardware Models for High-level Synthesis, Internal Representation of the Input Algorithm, and Understanding RTL to Gate Level design mapping. Basic concept of Static Timing Analysis (STA).

Partitioning : Introduction, Types of Partitioning, Classification of partitioning Algorithm, KL algorithm.

Floor-planning : Introduction, Sliced and non-sliced planning, Polish expression, Power planning, IO Planning

Placement : Introduction, classification of placement algorithms, partition based placement, timing / congestion aware Placement

Clock Tree Synthesis : Different topologies of Clock Tree Structure. Overview on Clock Mesh implementation for High Performance designs.Routing: Fundamental Concepts of Steiner trees, Two phases of Routing: Global routing & detailed routing, Routing Algorithms

Low Power Physical Design : Understanding Various Power Optimization algorithms (dynamic and Leakage). Overview on implementation and complexities involved in low power PD.

SOC Physical Design: Re-convergent model of VLSI SOC Design, SOC Physical design, advanced physical design of SOCs.

Text books

- 1. VLSI Physical Design Automation: Theory and Practice: Sadiq M. Sait, Habib Youssef, McGraw-Hill 2004.
- 2. VLSI Physical Design: From Graph Partitioning to Timing Closure: Jin Hu, Jens Lienig, Igor L. Markov, Andrew B. Kahng, Springer, Dordrecht 2011.
- 3. Handbook of Algorithms for Physical Design Automation: Charles J Alpert, Dinesh P Mehta, Sachin S Sapatnekar, CRC Press, 2008.
- 4. A Practical Approach to VLSI System on Chip (SoC) Design, Veena Chakravarthi, Springer International Publishing 2020

- 1. Physical Design Essentials: An ASIC Design Implementation Perspective: Khosrow Golshan, Springer, (2007)
- 2. Static Timing Analysis for Nanometer Designs: A Practical Approach: J. Bhasker and Rakesh Chadha, Springer, (2009).
- 3. Practical Problems in VLSI Physical Design Automation, Sung Kyu Lim, Springer, (2008), ISBN 978-1402066269
- 4. Algorithms for VLSI Design Automation: Sabih H. Gerez and John Wiley, (1998).
- 5. An Introduction to VLSI Physical Design: Majid Sarrafzadeh and C. K. Wong, McGraw Hill, (1996).
- 6. Algorithms for VLSI Physical Design Automation: Naveed Sherwani, Kluwer Academic Pub., (1999).





Syllabus for Semester II, M.Tech

(VLSI Design)

Course Code : ENT580-7/ENT581-7

Course : Industry Elective

L: 3 Hrs., P: 0 Hrs., Per week

Total Credits : 3

The course will be offered by an Industry expert on latest trends in Industry.





Syllabus for Semester II, M.Tech (VLSI Design)

Course Code : ENP582

L:0 Hrs., P:2 Hrs., Per week

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to:

- I. Apply fundamental principles to solve problems
- II. Design and execute an experimental procedure, work independently, interpret experimental results
- III. Draw a reasonable, accurate conclusion using suitable tools and technique

Practical / Case Studies / Mini projects

Course : Lab Practice - II

Total Credits : 1



Syllabus for Semester II, M.Tech (VLSI Design) Open Elective

Course Code : ENT599-2Course : Digital System Design with FPGAL : 3 Hrs., P : 0 Hrs., Per weekTotal Credits : 3

Course Outcomes

Upon the completion of this course, students will demonstrate the ability to :

- I. Design and analyze combinational, sequential and arithmetic circuits
- II. Understand digital system design flow, timing, synthesis and FPGA implementation issues.
- III. solve engineering problems in the area of digital system design.

Syllabus

Basic Digital Systems

Combinational Circuits, Sequential Circuits, Timing.

Digital System Design

Top down Approach to Design, Case study, Data Path, Control Path, Controller behavior and Design, Case study Mealy & Moore Machines, Timing of sequential circuits, Pipelining, Resource sharing.

Hardware Description language

Introduction, Behavioral, Data flow, Structural Models, Simulation Cycles, Process, Concurrent Statements, Sequential Statements, Loops, Sequential Circuits, FSM Coding, Library, Packages, Functions, Procedures, Test bench.

FSM Design: Controller (FSM), metastability, synchronization, FSM issues, timing issues, pipelining, resource sharing, case study.

FPGA FPGA : Architecture Xilinx and Altera, Logic block and routing architecture.

Text Books

- 1. A VHDL Primer, Third Edition : J. Bhasker, Prentice Hall, (1999).
- 2. Digital Systems Design Using VHDL, Second edition. Lizy Kurian John, Charles H. Roth, Cengage; (2012)
- 3. Fundamental of Digital Logic with VHDL Design, Third Edition, Stephen Brown, Zvonko Vranesic, McGraw Hill Education (2012)

- 1. An Engineering Approach to Digital Design : W. Fletcher, Prentice Hall
- 2. VHDL for Engineers, Kenneth L. Short, Pearson Education (2009)





Syllabus for Semester II, M.Tech (VISI Design)	
Course Code : ENP583	Course : Seminar
L : 0 Hrs., P : 2 Hrs., Per week	Total Credits : 1
Course Outcomes	+
Opon completion of this course, students should demonstrate the ability to	
I. Identify the contemporary topic pertaining to VLSI Design.	1
II. Present the topics with good written and oral communication skills.	
	1
	i I
	I
	1
	I
	I
	1
L	

Syllabus for Semester I / II, M.Tech

(VLSI Design)

Course Code : ENT577-1/ENT584-1

L: 2 Hrs., P: 0 Hrs., Per week

Course : Technical Communication Total Credits : 0

Course Outcomes

Students will be able to:

- I. Understand that how to improve Technical communication skills
- II. Utilize the technical writing and presentation skill/ techniques for the effective Technical Communication

Syllabus

Basics of technical writing : Planning and preparation, Structuring Paragraphs and Sentences, Breaking up long sentences, Word order, tense and voice, Removal ofredundancy and typos, Avoiding ambiguity and vagueness, Clarifying contributions, Highlighting your findings, Hedging and Criticizing, Paraphrasing

Sections of report / **articles :** Types of Articles, strategy for writing various sections of research articles: Abstracts, Graphical abstract, Introduction, Review of the Literature, Methods, Results and Discussion, Conclusions, Supplementary data, biography and other sections.

Tools for technical writing : Plotting tools, infographics tools, reference management tools, Plagiarism tools, understanding plagiarism report, report \article drafting tool like LATEX, Grammar checking tools.

Identification of journal : Understanding indexing, types of indexing, submission to publishing process flow, Selection of journal, criteria for selection, assistive tools.

Technical Presentation : Strategies & Techniques, interpersonal Communication, Class room presentation, Modes of Presentation, Methods of Presentation, Oral Communication & Voice Dynamics:

Public Speaking methods, Stimulus & Response, Clarity of substance, Encoding - Decoding process, Pronunciation Etiquette, Vowel - consonant sounds; Rising tone; Falling Tone, Flow in Speaking, Audience analysis & retention of audience interest, Audience participation: Quizzes & Interjections,

Professional Personality Attributes : Empathy; Considerateness; Leadership; Competence.

Case studies : C.V./Resume writing, Technical Proposal, Research articles and cover letter, Research funding proposal



- 1. Technical Communication Principles and Practices ,Meenakshi Raman & Sangeeta Sharma, Oxford Univ. Press, 2007, New Delhi.
- 2. Personality Development and Soft Skills, Barun K. Mitra, OUP, 2012, New Delhi.
- 3. How to Write and Publish a Scientific Paper, Day R (2006), Cambridge University Press
- 4. English for Writing Research Papers, Adrian Wallwork, Springer New York Dordrecht Heidelberg London, 2011
- 5. Spoken English- A Manual of Speech and Phonetics ,R.K.Bansal&J.B.Harrison, Orient Blackswan, 2013, New Delhi



Syllabus for Semester I / II, M.Tech

(VLSI Design)

Course Code : ENT577-2/ENT584-2Course : Innovation and EntrepreneurshipL : 2 Hrs., P : 0 Hrs., Per weekTotal Credits : 0

Course Outcomes

After attending the course students should be able to:

- I. Understand the logic and mechanics of a business enterprise
- II. Determine if they have the mind-set & preparation to be an entrepreneur
- III. Develop an understanding of the entrepreneurial process from conceptual stage to becoming an established business
- IV. Know about stages of technology evolution, product and business life cycles
- V. Develop an understanding of business functions essential for success of technology enterprises
- VI. Present Business Plan, Objective: Search for a scalable, repeatable & profitable business model

Syllabus

Unit - I

This module includes a welcome to the course, an orientation to our teaching approach and faculty, and an introduction to the fundamentals of innovation and entrepreneurship.

Introduction : entrepreneurship, entrepreneur, creativity, & innovation, The world's most innovative companies

Types of innovation, case studies, Entrepreneurs and strategic decisions, The opportunity analysis canvas

Unit - II

Entrepreneurial Mind set, Motivations, and Behaviors

This module explores entrepreneurial thinking with attention to entrepreneurial mind set, entrepreneurial motivations, and entrepreneurial behaviors.

Introduction to entrepreneurial mind set, motivations, and behaviors, Entrepreneurial motivations, Risk taking in entrepreneurial decision-making, Risk, uncertainty, and stakeholder involvement

Unit - III

Industry Understanding : This module examines how to recognize entrepreneurial opportunities based on market conditions and industry factors.



Introduction to industry understanding, Knowledge, Demand conditions, Industry life cycle, Industry structure, Competitive advantage,

Learning curve, Complementary assets, Reputation effects

Unit-IV

Customer Understanding and Business Modeling

This module introduces approaches to understanding customers, developing compelling solutions, and crafting winning business models.

Exploring real market needs, Satisfying real market needs, Strategic positioning, Strategic planning, Opportunity identification, Business Models Canvas, business model, business plan

- 1. "The Innovator's Dilemma" by Clayton Christensenm
- 2. "Out of Our Minds: Learning to be Creative" by Ken Robinson, Risk, uncertainty, and stakeholder involvement
- 3. The Entrepreneurial Mindset: Strategies for Continuously Creating Opportunity in an Age of Uncertainty by Rita Gunther McGrath and Ian MacMillan
- 4. "The E-Myth Revisited: Why Most Small Businesses Don't Work and What to Do About It" by Michael E. Gerber
- 5. "The Lean Startup: How Today's Entrepreneurs Use Continuous Innovation to Create Radically Successful Businesses" by Eric Ries
- 6. "Business Model Generation: A Handbook for Visionaries, Game Changers, and Challengers" by Alexander Osterwalder and Yves Pigneur
- 7. "Blue Ocean Strategy: How to Create Uncontested Market Space and Make Competition Irrelevant" by W. Chan Kim and Renee Mauborgne



Syllabus for Semester I / II, M.Tech

(VLSI Design)

Course Code : ENT577-3/ENT584-3

L: 2 Hrs., P: 0 Hrs., Per week

Course : Personality Development Total Credits : 0

Course Outcomes

At the end of this course.

- 1. Students will learn the importance and skills of verbal and non-verbal communication in a professional setting.
- II. Student will learn and apply the skill to write effective professional / workplace documents.
- III. Students will learn the generic skills required to work in a team.

Syllabus

Define Personality, Determinants of Personality Development, Perception - Definition, Perceptual Process Factors of Association - Relationship, Personality Traits, Developing Effective Habits.

Emotional Intelligence

Motivation, Introspection, Self-Assessment, Self-Appraisal and Self-development, Sigmund Freud Id, Ego and Super Ego. Self Esteem and Maslow, Self Esteem and Erik Erikson, Mind Mapping, Competency Mapping and 360 Degree Assessment, Types of Personalities - Introvert, Extrovert and Ambivert person, Effective Communication and Its key aspects.

Assertiveness, Decision making skills, Conflict : Process and Resolution, Leadership and Qualities of Successful Leader. Interpersonal Relationship, Personality - Spiritual journey beyond management of change, Good manners and Etiquettes, Effective Speech, Understanding Body language, projective positive body language Attitude - Concept - Significance - Factors affecting attitudes - Positive attitude - Advantage - Negative attitude - Disadvantages - Ways to develop positive attitude, Carl Jung's contribution to personality development theory.

Stress Management : Inroduction, Causes, stress management techniques, Time management : Importance of time management, Techniques of time management, Time Management styles.

- 1. Seven Habits of Highly Effective People Stephen Covey.
- 2. You can Win Shiv Khera
- 3. Three Basic Managerial Skills for all Hall of India Pvt. Ltd. New Delhi.
- 4. Hurlock Elizebeth B Personality Development Tata McGraw Hill, Ned Delhi.
- 5. Understanding Psychology : By Robert S Feldman. (Tata McGraw Hill Publishing)



- 6. Personality Development and Career management : By R. M. Onkar (S Chand Publications)
- 7. Social Psychology : By Robert S. Feldman. (Tata McGraw Hill Publishing)
- 8. McGraw Eh Basics Management Skills for all Printish Hall of India Pvt. Ltd. New Delhi.
- 9. Wehtlel David A and Kin S Kemerron Developing Managerial Skills Pearson Education, New Delhi.
- 10. Essentials of Business Communication Rajendra Pal and J. S. Korlhalli Sultan Chand and Sons, New Delhi.
- 11. Business Communication (Principles, Methods and Techniques) Nirmal Singh Deep and Deep Publications Pvt. Ltd., New Delhi.
- 12. Effective Business Communication H. Murphy.



NOTES

